

Application No. 09/802,792

20. (Amended) An integrated circuit wafer suitable for immediate dicing into at least one chip, comprising:

b3 a first chip area defined in a main surface of the wafer, the first chip area including structure related to a first photosite;

a groove defined in the wafer, the groove defining at least one edge of the first chip area; and

a light-transmissive planar layer disposed over the main surface, the planar layer forming a planar surface substantially parallel with the main surface, the planar layer extending over the groove.

31. (Amended) A method of making photosensitive chips for use in an imaging apparatus, comprising the steps of:

b4 providing an integrated circuit wafer, the wafer comprising a first chip area defined in a main surface of the wafer, the first chip area including structure related to a first photosite, and a groove defined in the wafer, the groove defining at least one edge of the first chip area;

providing a light-transmissive planar layer over the main surface, the planar layer forming a planar surface substantially parallel with the main surface, the planar layer extending over the groove; and

dicing the wafer along the groove to form a chip from the first chip area, a portion of the groove forming an edge of the chip, wherein a portion of the light-transmissive planar layer on the chip extends into the portion of the groove.

/ Please cancel claim 33.